



Attorney's Docket No. 02986.P028

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kenneth S. McElvain

Application No.: 10/626,031

Filing Date: July 23, 2003

For: Integrated Circuit Devices and  
Methods and Apparatuses for  
Designing Integrated Circuit Devices

Examiner: Not Yet Assigned

Art Unit: Not Yet Assigned

FIRST CLASS CERTIFICATE OF MAILING (37 C.F.R. § 1.8(a))

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INFORMATION DISCLOSURE STATEMENT

Sir:

Enclosed is a copy of Information Disclosure Citation Form PTO-1449 together with copies of the documents cited on that form. It is respectfully requested that the cited documents be considered and that the enclosed copy of Information Disclosure Citation Form PTO-1449 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s).

Pursuant to 37 C.F.R. § 1.97, the submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made and is not to be construed as an admission that the information cited in this statement is material to patentability.

Pursuant to 37 C.F.R. § 1.97, this Information Disclosure Statement is being submitted under one of the following (as indicated by an "X" to the left of the appropriate paragraph):

  X   37 C.F.R. §1.97(b).

       37 C.F.R. §1.97(c). If so, then enclosed with this Information Disclosure Statement is one of the following:

       A statement pursuant to 37 C.F.R. §1.97(e); or

       A check for \$180.00 for the fee under 37 C.F.R. § 1.17(p).

       37 C.F.R. §1.97(d). If so, then enclosed with this Information Disclosure Statement are the following:

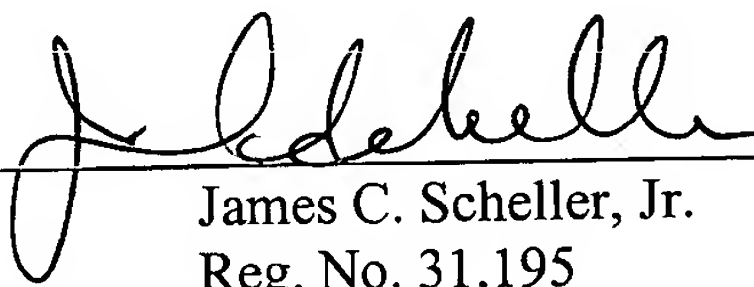
- (1) A statement pursuant to 37 C.F.R. §1.97(e); and
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If there are any additional charges, please charge Deposit Account No. 02-2666.

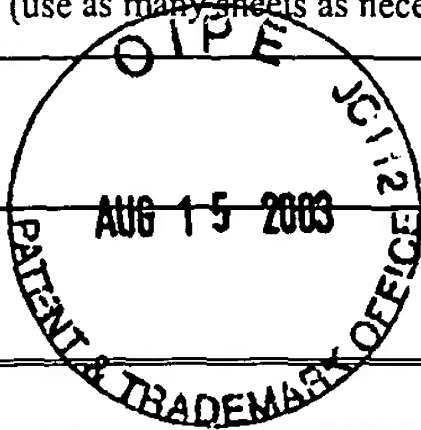
Respectfully submitted,

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<b>Substitute for Form 1449A/PTO (Modified)</b> (use as many sheets as necessary)		<b>Attorney Docket No.:</b> 02986.P028	<b>Application Number:</b> 10/626,031		
		<b>First Named Inventor:</b> Kenneth S. McElvain			
		<b>Filing Date:</b> July 23, 2003			
<b>U.S. PATENT DOCUMENTS</b>					
Exam. Initial*	Cite No. <sup>1</sup>	U.S. Patent Document	Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number      Kind Code <sup>2</sup> (If known)			

<b>OTHER ART – NO PATENT LITERATURE DOCUMENTS</b>			
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	Translation <sup>2</sup>
		Magma Design Automation, Inc., "Deep-Submicron Signal Integrity", white paper, 2002	
		Andrey V. Mezhiba, Eby G. Friedman, "Scaling Trands of On-Chip Power Distribution Noise", SLIP'02, April 6-7, 2002, San Diego, California, USA, pp.47-53	
		Sani R. Nassif, Onsi Fakhouri, "Technology Trends in Power-Grid-Induced Noise", SLIP'02, April 6-7, 2002, San Diego, California, USA, pp.55-59	
		Seongkyun Shin, Yungseon Eo, William R. Eisenstadt, Jongin Shim, "Analytical Signal Integrity Verification Models for Inductance-Dominant Multi-Coupled VLSI Interconnects", SLIP'02, April 6-7, 2002, San Diego, California, USA, pp.61-68	
		S. Khatri, A. Mehrotra, R. Brayton, A. Sangiovanni-Vincentelli, and R. Otten, "A novel VLSI layout fabric for deep sub-micron applications," in <i>Proceedings of the Design Automation Conference</i> , (New Orleans), June 1999.	
		Sunil P. Khatri, Robert K. Brayton, Alberto Sangiovanni-Vincentelli, "Cross-talk Immune VLSI Design using a Network of PLAs Embedded in a Regular Layout Fabric", IEEE/ACM International Conference on Computer Aided Design, ICCAD-2000, November 5-9, 2000, San Jose, CA, USA	

Examiner Signature		Date Considered	
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\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

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